

AMENDMENTS TO THE CLAIMS

This Claim Listing will replace all prior versions and listings of claims in the instant application:

1.-21. (Cancelled)

22. (Newly presented) Laminated glazing comprising two glass sheets and one or more thermoplastic interlayers, characterised in that light-emitting diodes (LEDs) are inserted between the two glass sheets, a connecting circuit being formed from at least one conductive layer deposited on one face of the glass sheets or of the thermoplastic interlayers, the conductive layer being divided in at least 2 distinct areas, each area being bound to an electrode.

23. (Newly Presented) Glazing according to Claim 22, characterised by one of the following:

- (a) the conductive layer has a thickness in the range of between 0.02 and 0.5 μ , and
- (b) the conductive layer has a thickness in the range of between 0.2 and 0.4 μ .

24. (Newly Presented) Glazing according to Claim 23, characterised by one of the following:

- (a) the conductive layer has a resistance in the range of between 2 and 80 Ω /sq.,
- (b) the conductive layer has a resistance in the range of between 10 and 80 Ω /sq., and
- (c) the conductive layer has a resistance in the range of between 12 and 20 Ω /sq.

25. (Newly Presented) Glazing according to Claim 22, characterised in that the conductive layer is applied on the transparent substrate and zones have been insulated from the rest of the layer by narrow insulating bands.

26. (Newly Presented) Glazing according to Claim 25, characterised by one of the following:

- (a) the insulating bands have a width in the range of between 0.01 and 3 mm,
- (b) the insulating bands have a width in the range of between 0.05 and 1.5, and
- (c) the insulating bands have a width in the range of between 0.1 and 0.8 mm.

27. (Newly Presented) Glazing according to Claim 22, characterised by one of the following:

- (a) the electronic components have a thickness less than or equal to 3 mm, and
- (b) the electronic components have a thickness less than or equal to 0.1 and 1.2 mm.

28. (Newly Presented) Glazing according to Claim 22, characterised in that the LEDs comprise several semiconductor chips in a casing.

29. (Newly Presented) Glazing according to Claim 28, characterised by one of the following:

- (a) the casing is dimensioned such that its length and/or a width are at least 10-times larger than its thickness;
- (b) the casing is dimensioned such that its length and/or a width are at least 20-times larger than its thickness; and
- (c) the casing is dimensioned such that its length and/or a width are at least 40-times larger than its thickness;

30. (Newly Presented) Glazing according to Claim 28, characterised by one of the following:

- (a) the casing has a length and/or a width in the range between 5 and 100 mm;

- (b) the casing has a length and/or a width in the range between 15 and 75 mm; and
- (c) the casing has a length and/or a width in the range between 25 and 50 mm;

31. (Newly Presented) Glazing according to Claim 22, characterised in that a switch actuating the power supply of the electronic component is formed by a zone of the conductive layer insulated from the rest of the conductor layer by narrow bands.